# SMT3/SMTE3

# **Surface Mount Tactile Switches**





#### ■ Features -

- 1. Compatible With Lead-Free, Reflow Soldering Heat-resistance resin for lead-free soldering.
- 2. Washable (SMTE3 Series)
- 3. J-Lead Terminal Pins For High-Density Mounting
- 4. Anti-Static Electricity (SMTE3 Series) Ground terminal is provided to prevent damage to element caused by static electricity.

#### ■ Specifications -

Rating	Max.	0.6 VA max. (24 VDC max. 30 mA max.) (Resistive load)	
	Min.	Silver plated contacts	1 mA 5 VDC(Resistive load)
		Gold plated contacts	10 μA 5 VDC(Resistive load)
Initial contact resistance		100mΩ max.	(1.5mA 200µVAC)
Dielectric strength		250VAC 1 minute	
Insulation resistance		100MΩ min.	(100VDC)
Electrostatic capacity		5pF max.	
Electrical life		100,000 operations	
Stroke	SMT3	0.25mm	
	SMTE3	0.5mm	
Operating force	SMT3	1.18±0.39 N	
	SMTE3	1.96±0.98 N	
Operating temperature range		-25∼+70°C	
Storage temperature range		-40∼+85°C	

■ Structure -

#### ■ Part Numbering

### SMT E

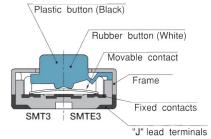
G 3 - 01 E - Z

Series code Structure Contact plating Series No. Registration No. Packaging specs.

None	Standard type ( Plastic button )	
E	Immersion washable (Rubber button)	

None	Silver plated
G	Gold plated





#### ■ Table of Part Numbers

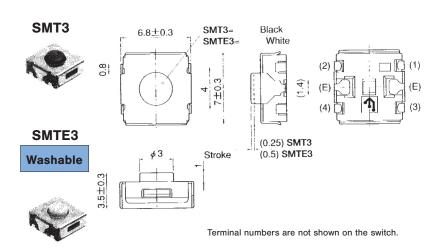
Structure	Packaging specifications	
Structure	Stick	Emboss taping
Standard type	SMT3-01-Z	SMT3-01E-Z ★ SMTG3-01E-Z
Immersion washable	SMTE3-01-Z ★ SMTEG3-01-Z	SMTE3-01E-Z ★ SMTEG3-01E-Z

#### ■Pad Layouts

(Top view)

Ground terminals	Without	With
Part No.	SMT3 • SMTE3 SMTG3 • SMTEG3	SMTE3 SMTEG3
Pattern dimensions	3.2 3.6 3.2	3.2 3.6 3.2 (1) (2) (2) (E) (G) (4)

#### **SPST**



	Switchng function	
Part No.		Push
SMT3-01-Z SMT3-01E-Z SMTG3-01E-Z SMTE3-01-Z SMTE3-01E-Z SMTEG3-01-Z SMTEG3-01E-Z	OFF	(ON)
Connecting terminals		1 - 3
Circuit diagrams	(1) O (2) (3) O (4) (E) O (E)	

(ON): Momentary

(E) : Ground terminal (SMTE3 and SMTEG3 series)

#### **■**Soldering Specifications

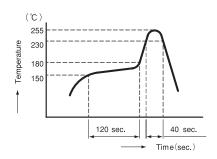
(1) Manual Soldering

Device: Soldering iron

 $1350^{\circ}$ C ±  $10^{\circ}$ C;  $3 \pm 0.5$  seconds

(2) Reflow Soldering

Device: Inline or batch system



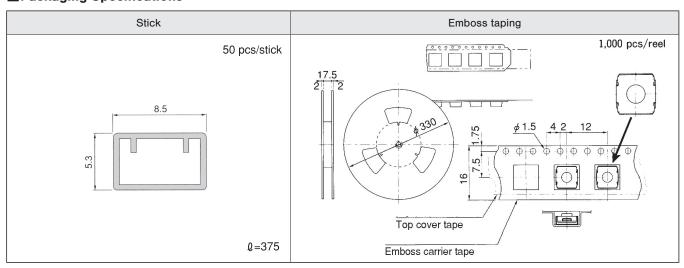
Apply reflow soldering up to 2 times max.

#### **■**Flux Cleaning

Since the **SMT3** series is not process sealed, be sure to use low-residue flux.

- (1) Solvent: Fluorine or Alcohol type Cleaning with other solvents or water is not possible.
- (2) Cleaning after soldering should be done after the terminal temperature falls to 90°C or below, or after leaving the switch for five minutes or longer at room temperature. Cleaning temperature: 43°C, max.
- (3) Do not use ultrasonic cleaning.

#### ■ Packaging Specifications



When ordering, tape packaged version shall be supplied by request. Minimum packaging quantity for reel packaging is 1,000pcs per reel.

# **Mouser Electronics**

**Authorized Distributor** 

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# Nidec:

SMT3-01-Z SMT3-01E-Z SMTE3-01E-Z SMTE3-01-Z SMTEG3-01E-Z SMTEG3-01-Z SMTG3-01E-Z